# **Surface Mount Ultrafast Power Rectifier**

This SMA flat lead ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

#### **Features**

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile Maximum Height of 1.1 mm
- Small Footprint Footprint Area of 13.5 mm<sup>2</sup>
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

# **Mechanical Characteristics:**

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

#### **Applications**

• Switching Power Supplies including Mini-adapters and Displays

1

- Instrumentation
- Engine Control Recirculation Diodes
- Freewheeling Diode Where Space is at a Premium



# ON Semiconductor®

www.onsemi.com

# ULTRAFAST RECTIFIER 2.0 AMPERE 200 VOLTS



SMA-FL CASE 403AA STYLE 6

#### MARKING DIAGRAM



P22 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)

# ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NHPAF220T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel
NRVHPAF220T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	200	V
Average Rectified Forward Current (T <sub>L</sub> = 130°C)	Io	2.0	Α
Peak Repetitive Forward Current (Rated V <sub>R</sub> , Square Wave, 20 kHz) T <sub>L</sub> = 125°C	I <sub>FRM</sub>	4.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	60	Α
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	T <sub>J</sub>	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	$\Psi_{\sf JCL}$	29	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	80	°C/W

<sup>1. 1</sup> inch square pad size  $(1 \times 0.5)$  inch) for each lead on FR4 board.

# **ELECTRICAL CHARACTERISTICS**

		Va	lue	
Characteristic	Symbol	T <sub>J</sub> = 25°C	T <sub>J</sub> = 125°C	Unit
Maximum Instantaneous Forward Voltage (Note 2) (i <sub>F</sub> = 2.0 A)	VF	1.00	0.85	V
Maximum Instantaneous Reverse Current (Note 2) (V <sub>R</sub> = 200 V)	I <sub>R</sub>	0.5	35	μΑ
Reverse Recovery Time $I_F = 2.0 \text{ A}, V_R = 30 \text{ V}, \text{ dl/dt} = 50 \text{ A/}\mu\text{s}, T_J = 25^{\circ}\text{C}$	t <sub>rr</sub>	3	60	ns
Reverse Recovery Time $I_F = 2.0 \text{ A}, V_R = 30 \text{ V}, \text{ dl/dt} = 50 \text{ A/}\mu\text{s}, T_J = 125^{\circ}\text{C}$	t <sub>rr</sub>	5	60	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>2.</sup> Pulse Test: Pulse Width  $\leq$  380  $\mu$ s, Duty Cycle  $\leq$  2.0%.

### **TYPICAL CHARACTERISTICS**

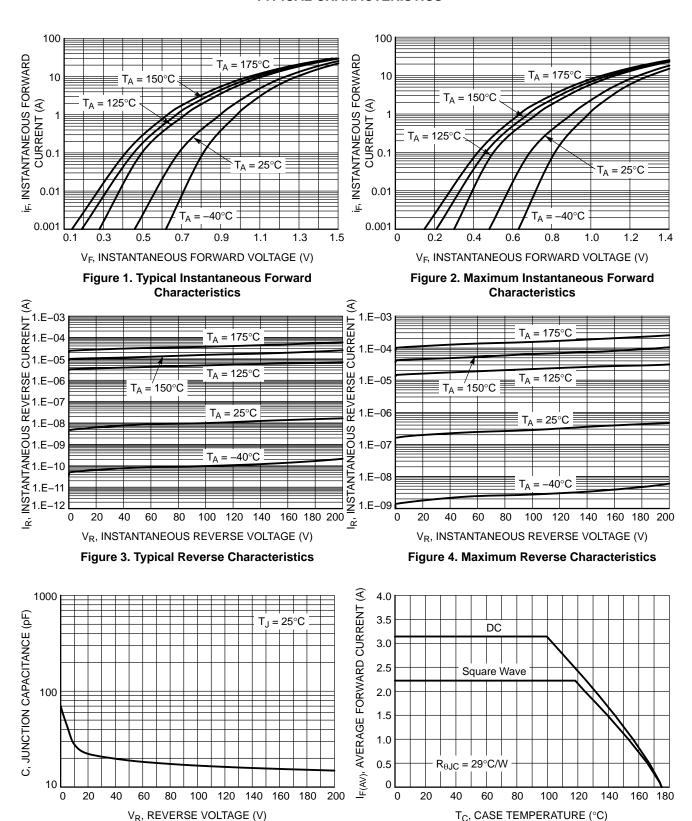
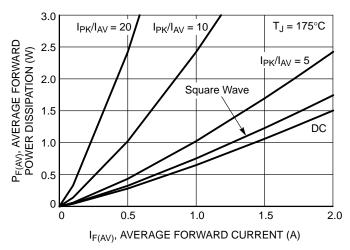


Figure 5. Typical Junction Capacitance

# **TYPICAL CHARACTERISTICS**



**Figure 7. Forward Power Dissipation** 

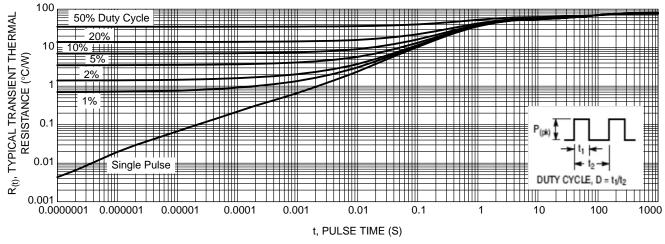
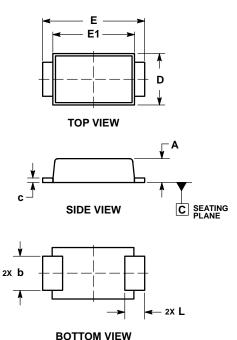


Figure 8. Typical Transient Thermal Response, Junction-to-Ambient

### PACKAGE DIMENSIONS

# SMA-FL CASE 403AA **ISSUE O**

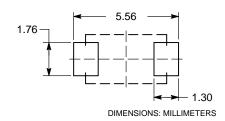


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- CONTROLLING DIMENSION: MILLIMETERS.

_	MILLIMETERS		
DIM	MIN	MAX	
Α	0.90	1.10	
b	1.25	1.65	
С	0.15	0.30	
D	2.40	2.80	
Е	4.80	5.40	
E1	4.00	4.60	
L	0.70	1.10	

#### **RECOMMENDED SOLDER FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the (III) are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

# **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative